

EAST Search History**EAST Search History (Prior Art)**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	"7307128"	USPAT	OR	OFF	2010/05/22 19:55
L2	1146	hitachi adj chemical.AS.	US-PGPUB; USPAT; DERWENT	OR	ON	2010/05/22 20:26
L3	1994	epoxy near sealant	US-PGPUB; USPAT; DERWENT	OR	ON	2010/05/22 20:26
L4	4	2 and 3	US-PGPUB; USPAT; DERWENT	OR	ON	2010/05/22 20:26
L17	345	257/793.CCLS.	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:30
L18	0	257/787, 257/789, 257/792. CCLS.	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:30
L19	2645	257/787.CCLS.	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:30
L20	367	257/789.CCLS.	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:30
L21	213	257/792.CCLS.	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:31
L22	11	19 and 20 and 21	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:31
L23	0	3 and 22	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:31
L24	872	epoxy near (alkoxy or hydrocarbon)	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:32
L25	602238	epoxy or bisphenol	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:32
L26	0	20 and 24	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:32
L27	288	20 and 25	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:32

L28	596	523/457.CCLS.	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:45
L29	710	523/466.CCLS.	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:45
L30	132	523/203.CCLS.	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:45
L31	376	523/404.CCLS.	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:46
L44	843	528/14.CCLS.	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:50
L45	1246	528/34.CCLS.	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:50
L46	295	528/97.CCLS.	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:50
L47	6	28 and 31	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:50
L49	460	106/287.12	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:50
L50	724	156/329	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:51
L51	0	525/476, "477", "481", "533". CCLS.	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:51
L52	518	525/476.CCLS.	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:51
L53	628	525/481.CCLS.	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:51
L54	976	525/533.CCLS.	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:51
L55	6	24 and 29	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:52
L56	1	24 and 46	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:52
L57	0	24 and "843"	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:52

L58	1	24 and 44	US-PGPUB; USPAT; DERWENT	NEAR	ON	2010/05/22 20:52
L66	2464	427/387.CCLS.	USPAT	OR	OFF	2010/05/22 20:53
L67	931	25 and 66	USPAT	OR	OFF	2010/05/22 20:54
S1	2	"6207789"	USPAT	OR	OFF	2008/08/06 09:01
S2	2	"20060214153"	US-PGPUB; USPAT	OR	OFF	2008/08/06 09:03
S3	3	"2004090033"	DERWENT	OR	OFF	2008/08/06 09:04
S4	1	"20030201548"	US-PGPUB; USPAT	OR	OFF	2008/08/06 09:38
S5	1322	epoxy near sealant	US-PGPUB; USPAT	OR	OFF	2008/08/06 09:45
S6	29	triphenylphosphine and (silane-coupling adj agent)	US-PGPUB; USPAT	OR	OFF	2008/08/06 09:46
S7	0	S5 and S6	US-PGPUB; USPAT	OR	OFF	2008/08/06 09:46
S8	25675	silicon near10 polymer	US-PGPUB; USPAT	OR	OFF	2008/08/07 13:10
S9	1406	epoxy near (sealant or encapsulate)	US-PGPUB; USPAT	OR	OFF	2008/08/07 13:10
S10	21	S8 and S9	US-PGPUB; USPAT	OR	OFF	2008/08/07 13:11
S11	11672	silicon near10 polymer	EPO; JPO; DERWENT	OR	OFF	2008/08/07 13:11
S12	300	epoxy near (sealant or encapsulate)	EPO; JPO; DERWENT	OR	OFF	2008/08/07 13:11
S13	1	S11 and S12	EPO; JPO; DERWENT	OR	OFF	2008/08/07 13:11
S14	1	"05283560"	US-PGPUB; USPAT	OR	OFF	2008/08/07 14:24
S15	1	"05283560"	JPO	OR	OFF	2008/08/07 14:24
S16	492	trimethoxysilane or methyltriethoxysilane	JPO	OR	OFF	2008/08/07 16:23
S17	22	epoxy near (sealant or encapsulate)	JPO	OR	OFF	2008/08/07 16:23
S18	0	S16 and S17	JPO	OR	OFF	2008/08/07 16:23
S19	15112	trimethoxysilane or methyltriethoxysilane	US-PGPUB; USPAT	OR	OFF	2008/08/07 16:23
S20	1406	epoxy near (sealant or encapsulate)	US-PGPUB; USPAT	OR	OFF	2008/08/07 16:23
S21	15	S19 and S20	US-PGPUB; USPAT	OR	OFF	2008/08/07 16:23

S22	1	"6040395"	US-PGPUB; USPAT	OR	OFF	2008/08/11 08:05
S23	3	"2003037976"	DERWENT	OR	OFF	2008/08/11 08:13
S24	0	organoalkoxysilane near (sealant or encapsulate)	US-PGPUB; USPAT; DERWENT	OR	OFF	2008/08/11 08:52
S25	0	organoalkoxysilane near (seal \$or encapsulate)	US-PGPUB; USPAT; DERWENT	OR	OFF	2008/08/11 08:52
S26	0	alkoxysilane near (seal\$or encapsulate)	US-PGPUB; USPAT; DERWENT	OR	OFF	2008/08/11 08:52
S27	0	oxysilane near (seal\$or encapsulate)	US-PGPUB; USPAT; DERWENT	OR	OFF	2008/08/11 08:52
S28	1	"20030201548"	US-PGPUB; USPAT	OR	OFF	2009/08/19 08:16
S29	9	((SEIICHI) near2 (AKAGI)).INV.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/08/19 08:40
S30	29	((MITSUO) near2 (KATAYOSE)). INV.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/08/19 08:40
S31	1	((TAKATOSHI) near2 (IKEUCHI)).INV.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/08/19 08:40
S32	3	((YOSHINORI) near2 (ENDOU)). INV.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/08/19 08:40
S33	1	((RYOUICHI) near2 (IKEZAWA)). INV.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/08/19 08:40
S34	777	anthracene adj compound	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:40
S35	2	reduced near10 (anthracene adj compound)	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:40
S36	0	dihydrogenat\$ near10 (anthracene adj compound)	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:40
S37	0	dihydrogenated near10 (anthracene adj compound)	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:40
S38	0	dihydrogenated near (anthracene adj compound)	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:40
S39	0	reduced near(anthracene adj compound)	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:40
S40	0	reduced near (anthracene adj compound)	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:40
S41	3296658	semiconductor or electronic	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:41

S42	0	S35 and S41	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:41
S43	342	S34 and S41	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:41
S44	2853344	reduce or dihydrogenated	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:42
S45	157	S43 and S44	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:42
S46	509809	epoxy	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:42
S47	17	S45 and S46	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:42
S48	1635	epoxy near sealant	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:42
S49	0	S45 and S48	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:42
S50	7774	anthracene and semiconductor	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:46
S51	509809	epoxy	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:47
S52	3278	S50 and S51	US-PGPUB; USPAT; DERWENT	OR	OFF	2009/08/19 10:47
S53	1540	epoxy near (sealant or encapsulate)	US-PGPUB; USPAT	OR	OFF	2009/08/19 10:47
S54	1	"7307128"	USPAT	OR	OFF	2010/04/01 09:30
S55	1	("6239245").PN. OR ("7307128").URPN.	US-PGPUB; USPAT; USOCR	NEAR	ON	2010/04/01 09:30
S56	1	("6239245").PN. OR ("7307128").URPN.	US-PGPUB; USPAT; USOCR	NEAR	ON	2010/04/01 09:31
S57	4	"1226815"	US-PGPUB; USPAT; USOCR	NEAR	ON	2010/04/01 09:32
S58	5	"1154908"	US-PGPUB; USPAT; USOCR	NEAR	ON	2010/04/01 09:32
S59	1	dihydroanthracenediol	US-PGPUB; USPAT; USOCR	NEAR	ON	2010/04/01 09:40
S60	0	dihydroanthracene adj epoxy	US-PGPUB; USPAT; USOCR	NEAR	ON	2010/04/01 12:11
S61	0	dihydroanthracene near10 epoxy	US-PGPUB; USPAT; USOCR	NEAR	ON	2010/04/01 12:12

S62	0	dihydroanthracene near10 epoxy	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2010/04/01 12:12
S63	11	dihydroanthracene near10 epoxy	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2010/04/01 12:12
S64	123576	sealant	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2010/04/01 12:36
S65	0	S63 and S64	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2010/04/01 12:36
S66	1404	dihydroanthracene	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2010/04/01 12:36
S67	21	S64 and S66	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2010/04/01 12:36
S68	126	523/203.CCLS.	USPAT	OR	OFF	2010/05/21 16:45
S69	670	523/400.CCLS.	USPAT	OR	OFF	2010/05/21 16:45

EAST Search History (Interference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L5	126	523/203.CCLS.	USPAT; UPAD	OR	OFF	2010/05/22 20:26
L6	677	523/400.CCLS.	USPAT; UPAD	OR	OFF	2010/05/22 20:26
L7	3	((SEI CHI) near2 (AKAGI)).INV.	USPAT; UPAD	OR	OFF	2010/05/22 20:26
L8	18	((MITSUO) near2 (KATAYOSE)). INV.	USPAT; UPAD	OR	OFF	2010/05/22 20:26
L9	1	((YOSHINORI) near2 (ENDOU)). INV.	USPAT; UPAD	OR	OFF	2010/05/22 20:27
L10	0	((RYOUI CHI) near2 (IKEZAWA)). INV.	USPAT; UPAD	OR	OFF	2010/05/22 20:27

L11	0	dihydroanthacene near10 epoxy	USPAT; UPAD	NEAR	ON	2010/05/22 20:27
L12	3223	sealant near10 epoxy	USPAT; UPAD	NEAR	ON	2010/05/22 20:27
L13	1	5 and 6	USPAT; UPAD	NEAR	ON	2010/05/22 20:27
L14	0	5 and 9	USPAT; UPAD	NEAR	ON	2010/05/22 20:27
L15	0	5 and 12	USPAT; UPAD	NEAR	ON	2010/05/22 20:28
L16	313	257/793.CCLS.	USPAT; UPAD	NEAR	ON	2010/05/22 20:29
L32	546	523/457.CCLS.	USPAT; UPAD	NEAR	ON	2010/05/22 20:46
L33	677	523/466.CCLS.	USPAT; UPAD	NEAR	ON	2010/05/22 20:46
L34	126	523/203.CCLS.	USPAT; UPAD	NEAR	ON	2010/05/22 20:47
L35	364	523/404.CCLS.	USPAT; UPAD	NEAR	ON	2010/05/22 20:47
L36	17	12 and 32	USPAT; UPAD	NEAR	ON	2010/05/22 20:47
L37	23	12 and 33	USPAT; UPAD	NEAR	ON	2010/05/22 20:47
L38	0	12 and 34	USPAT; UPAD	NEAR	ON	2010/05/22 20:47
L39	3	12 and 35	USPAT; UPAD	NEAR	ON	2010/05/22 20:47
L40	486	156/329.CCLS.	USPAT; UPAD	NEAR	ON	2010/05/22 20:49
L41	800	528/14.CCLS.	USPAT; UPAD	NEAR	ON	2010/05/22 20:49
L42	5	12 and 40	USPAT; UPAD	NEAR	ON	2010/05/22 20:49
L43	3	12 and 41	USPAT; UPAD	NEAR	ON	2010/05/22 20:49
L48	800	528/14.CCLS.	USPAT; UPAD	NEAR	ON	2010/05/22 20:50
L59	428	106/287.12	USPAT; UPAD	NEAR	ON	2010/05/22 20:52
L60	3489	anthracene and semiconductor	USPAT; UPAD	OR	OFF	2010/05/22 20:52
L61	2	48 and 60	USPAT; UPAD	OR	OFF	2010/05/22 20:53
L62	1074	"49" and 60	USPAT; UPAD	OR	OFF	2010/05/22 20:53
L63	2	59 and 60	USPAT; UPAD	OR	OFF	2010/05/22 20:53
L64	2474	427/387.CCLS.	USPAT; UPAD	OR	OFF	2010/05/22 20:53
L65	11	60 and 64	USPAT; UPAD	OR	OFF	2010/05/22 20:53

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